

# UP04401

## Silicon PNP epitaxial planar transistor

For general amplification

### ■ Features

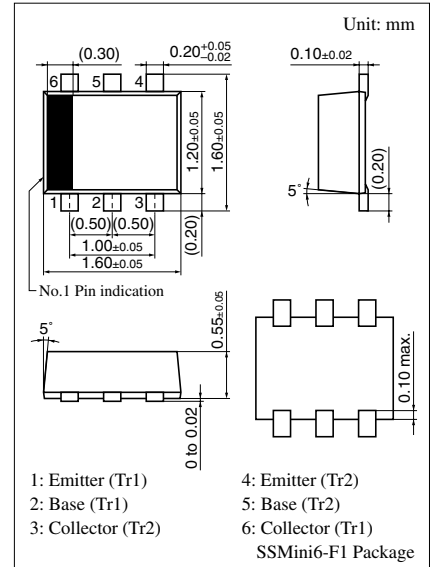
- Two elements incorporated into one package (Each transistor is separated)
- Reduction of the mounting area and assembly cost by one half

### ■ Basic Part Number of Element

- 2SB0709A (2SB709A) × 2 elements

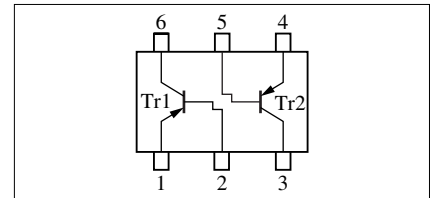
### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

	Parameter	Symbol	Rating	Unit
Rating of element	Collector to base voltage	$V_{CBO}$	-60	V
	Collector to emitter voltage	$V_{CEO}$	-50	V
	Emitter to base voltage	$V_{EBO}$	-7	V
	Collector current	$I_C$	-100	mA
	Peak collector current	$I_{CP}$	-200	mA
Total	Total power dissipation	$P_T$	125	mW
	Junction temperature	$T_j$	125	$^\circ\text{C}$
	Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$



Marking Symbol: 5K

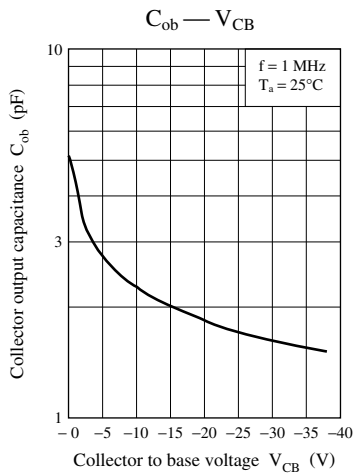
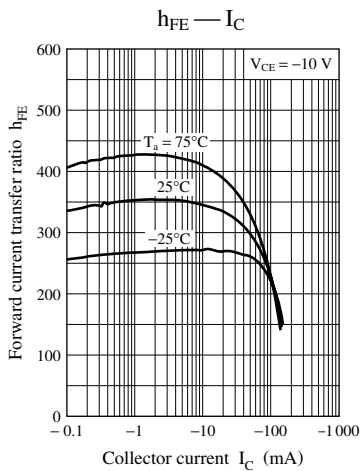
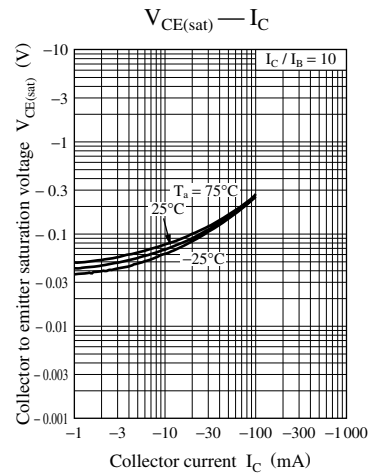
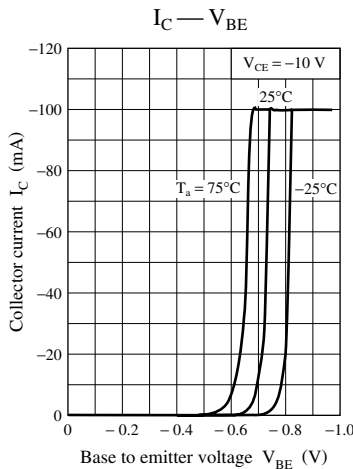
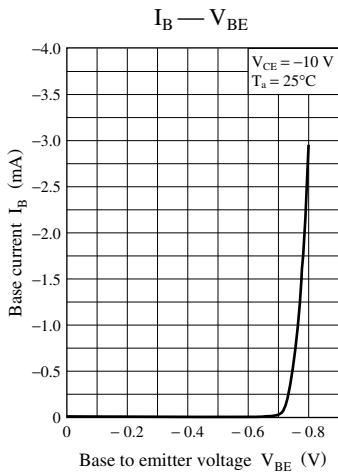
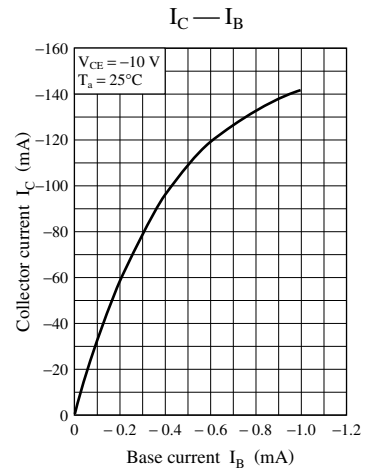
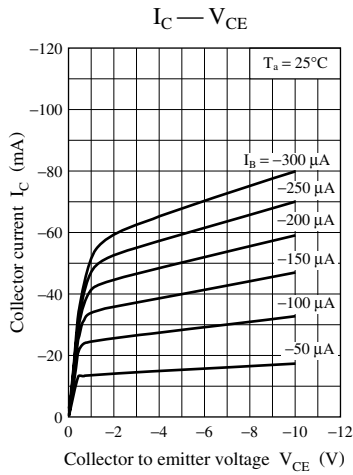
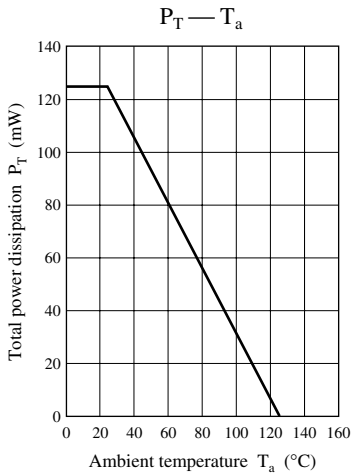
Internal Connection



### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector to base voltage	$V_{CBO}$	$I_C = -10 \mu\text{A}, I_E = 0$	-60			V
Collector to emitter voltage	$V_{CEO}$	$I_C = -2 \text{mA}, I_B = 0$	-50			V
Emitter to base voltage	$V_{EBO}$	$I_E = -10 \mu\text{A}, I_C = 0$	-7			V
Collector cutoff current	$I_{CBO}$	$V_{CB} = -20 \text{V}, I_E = 0$			-0.1	$\mu\text{A}$
	$I_{CEO}$	$V_{CE} = -10 \text{V}, I_B = 0$			-100	
Forward current transfer ratio	$h_{FE}$	$V_{CE} = -10 \text{V}, I_C = -2 \text{mA}$	180		390	—
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = -100 \text{mA}, I_B = -10 \text{mA}$		-0.3	-0.5	V
Collector output capacitance	$C_{ob}$	$V_{CB} = -10 \text{V}, I_E = 0, f = 1 \text{MHz}$		2.7		pF
Gain bandwidth product	$f_T$	$V_{CB} = -10 \text{V}, I_E = 1 \text{mA}, f = 200 \text{MHz}$		80		MHz

Note) The part number in the parenthesis shows conventional part number.



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